

REV.	MODIFICATION	DATE	DRAW
XA	INITIAL RELEASE	2021.02.03	Michael
XB	MODIF SPEC.	2021.06.18	Michael

HALOGEN FREE **LEAD FREE**

- NOTES**
- MATERIAL:**
HOUSING: THERMOPLASTIC UL94V-0
CONTACT: HIGH-PERFORMANCE COPPER ALLOY
LATCH: STAINLESS STEEL
PEG: STAINLESS STEEL
 - FINISH:**
CONTACT: GOLD PLATING ON CONTACT AREA (SEE NOTE 4)
1u"~3u" GOLD PLATING ON SOLDER AREA
NICKEL UNDER PLATING OVER ALL (SEE TABLE 1)
PEG: 50u"~150u" MATTE TIN PLATING OVER ALL
50u"~150u" NICKEL UNDER PLATING OVER ALL
 - MSL LEVEL:**
MSL (MOISTURE SENSITIVITY LEVEL)=1
 - PART NO.:**
D5ASX-262XX-XX52
- CONTACT AREA PLATING SPEC**
- | | |
|----------|-----------|
| 01: GOLD | 1u" Min. |
| 03: GOLD | 3u" Min. |
| 05: GOLD | 5u" Min. |
| 10: GOLD | 10u" Min. |
| 15: GOLD | 15u" Min. |
| 20: GOLD | 20u" Min. |
| 30: GOLD | 30u" Min. |
- PACKING**
P: TAPE REEL
HOUSING COLOR
1: BLACK
2: NATURAL

DIMENSION IN mm [Inch]	PROD. SPEC. SP-D5XXXL1
TOLERANCE UNLESS OTHERWISE SPECIFIED	PKG. SPEC. PK-D5XXX-XXX
N	WITH "@LTK" 90u"~150u"
A	WITHOUT "@LTK" 50u"~150u"
0(NUMBER ZERO)	WITH "@LTK" 50u"~150u"
X	TRADEMARK CONTACT NICKEL FINISH

ARGOSY RESEARCH INC.

TITLE: DDR5 5.2H STD CONNECTOR

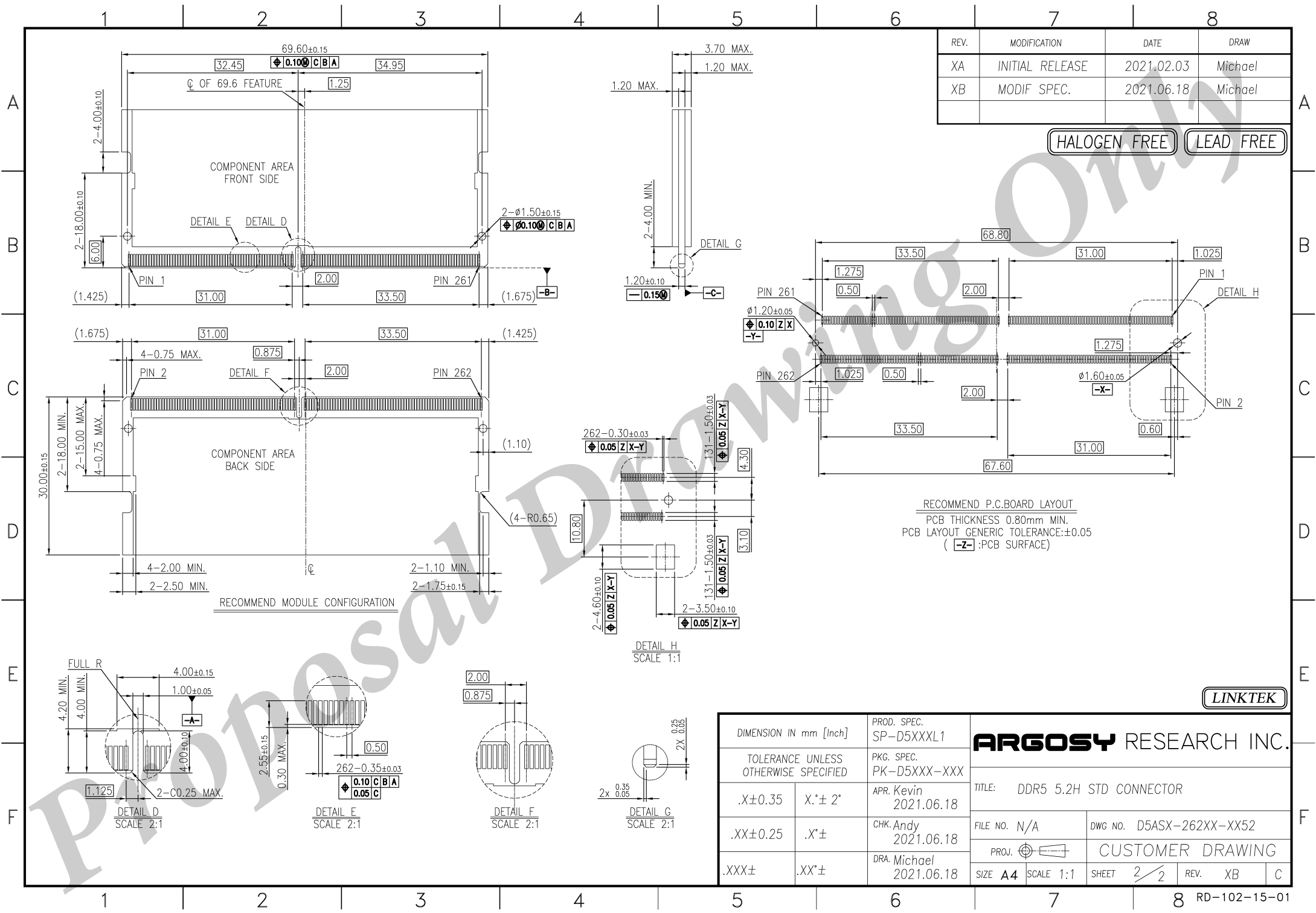
FILE NO. N/A DWG NO. D5ASX-262XX-XX52

PROJ. CUSTOMER DRAWING

SIZE A4 SCALE 1:1 SHEET 1/2 REV. XB C

TABLE 1

N	WITH "@LTK"	90u"~150u"
A	WITHOUT "@LTK"	50u"~150u"
0(NUMBER ZERO)	WITH "@LTK"	50u"~150u"
X	TRADEMARK	CONTACT NICKEL FINISH

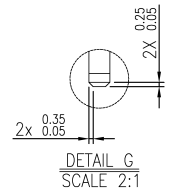
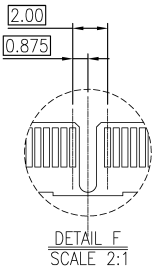
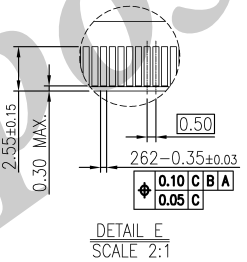
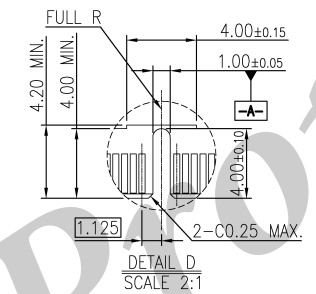


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RECOMMEND P.C.BOARD LAYOUT
 PCB THICKNESS 0.80mm MIN.
 PCB LAYOUT GENERIC TOLERANCE:±0.05
 (-Z- :PCB SURFACE)

RECOMMEND MODULE CONFIGURATION



DIMENSION IN mm [Inch]		PROD. SPEC. SP-D5XXL1
TOLERANCE UNLESS OTHERWISE SPECIFIED		PKG. SPEC. PK-D5XXX-XX
.X±0.35	X.*± 2°	APR. Kevin 2021.06.18
.XX±0.25	.X*±	CHK. Andy 2021.06.18
.XXX±	.XX*±	DRA. Michael 2021.06.18

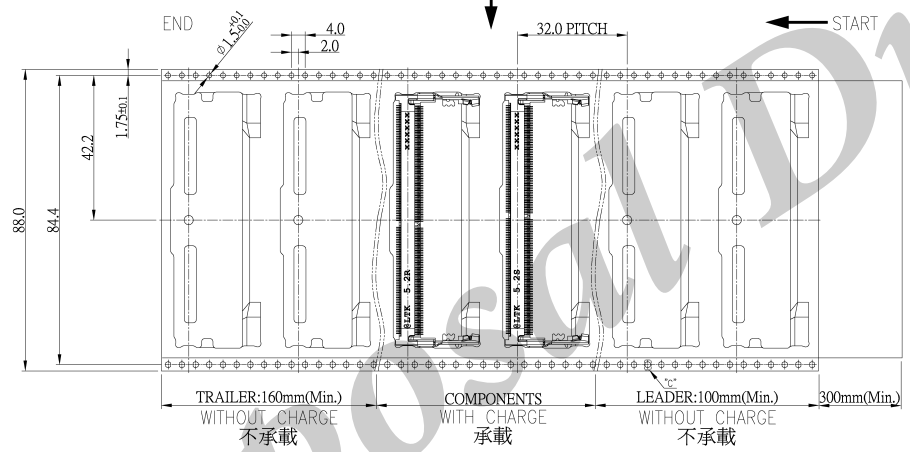
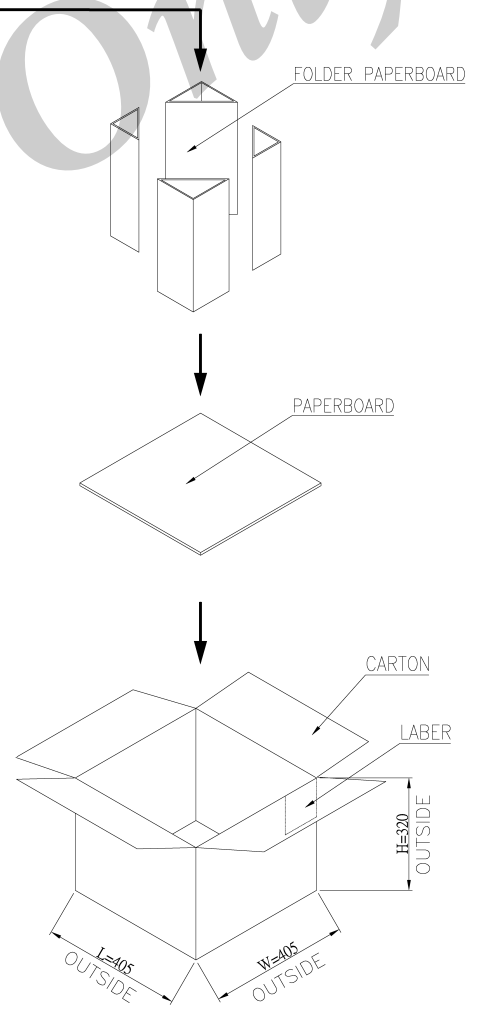
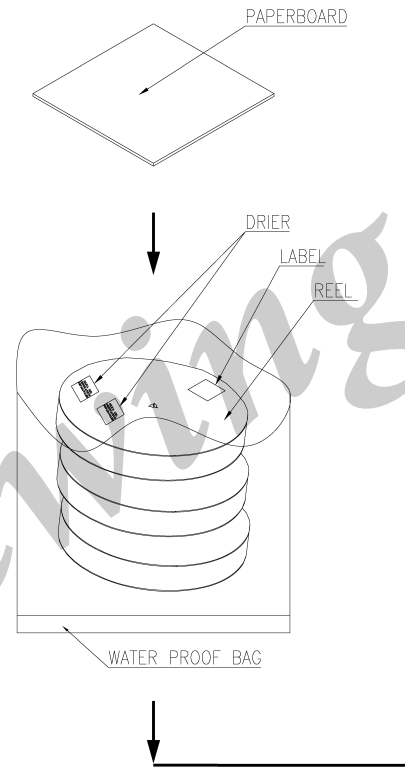
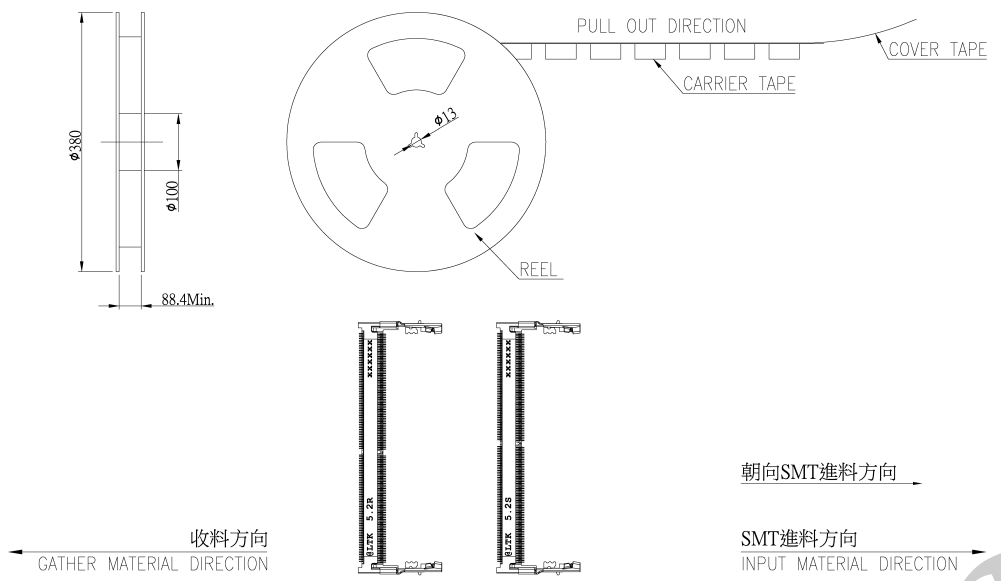
ARGOSY RESEARCH INC.

TITLE: DDR5 5.2H STD CONNECTOR			
FILE NO. N/A	DWG NO. D5ASX-262XX-XX52		
PROJ.	CUSTOMER DRAWING		
SIZE A4	SCALE 1:1	SHEET 2/2	REV. XB C

LINKTEK

HALOGEN FREE LEAD FREE

F
E
D
C
B
A



PART NO.	PCS/REEL	REEL/CARTON	PCS/CARTON
D5XRX-262XX-XP52X	450	3	1.35K
D5XSX-262XX-XP52X	450	3	1.35K

ARGOSY RESEARCH INC.	產品名稱 TITLE	PACKING FOR T/P DDR5 SO.DIMM CONNECTOR 5.2H REEL: 88.0 mm	案號 FILE NO.	N/A	更改 REV	XA	張數 SHEET	1 / 1	SIZE				
	包裝規範(PACKING LIST)	圖號 DWG. NO.	PK-D5XXX-003	審核 APPROVE	Kevin 2021.02.03	核對 CHECK	Andy 2021.02.03	製圖 DRAW	Michael 2021.02.03	A4	XA 更改 REV	INITIAL RELEASE 設變內容 MODIFICATION	2021.02.03 日期 DATE